



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C560JB8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 56pF, 50V, ±5%, C0G, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>560</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| 1 | Series        | Samsung Multi-layer Ceramic Capacitor |            |                 |    |       |         |              |
|---|---------------|---------------------------------------|------------|-----------------|----|-------|---------|--------------|
| 2 | Size          | 0603 (inch cod                        | de) L: 1.6 | ± 0.1 mm        | W: | 8.0   | ± 0.1   | mm           |
|   |               |                                       |            |                 |    |       |         |              |
| 3 | Dielectric    | C0G                                   | 8          | Inner electrode |    | Ni    |         |              |
| 4 | Capacitance   | <b>56</b> pF                          |            | Termination     |    | Cu    |         |              |
| ⑤ | Capacitance   | ±5 %                                  |            | Plating         |    | Sn 10 | 0%      | (Pb Free)    |
|   | tolerance     |                                       | 9          | Product         |    | Norma | al      |              |
| 6 | Rated Voltage | 50 V                                  | 10         | Special         |    | Reser | ved for | future use   |
| 7 | Thickness     | $0.8 \pm 0.1$                         | mm ①       | Packaging       |    | Cardb | oard T  | ype, 7" reel |

## **B. Samsung Reliablility Test and Judgement condition**

|                                    | Performance  | Test condition                       |  |  |  |  |  |
|------------------------------------|--|--------------------------------------|--|--|--|--|--|
| Capacitance                        | Within specified tolerance   | 1Mb±10% 0.5~5Vrms                    |  |  |  |  |  |
| Q                                  | 1000 min   |                                      |  |  |  |  |  |
| Insulation                         | 10,000Mohm or 500Mohm·μF   | Rated Voltage 60~120 sec.            |  |  |  |  |  |
| Resistance                         | Whichever is Smaller   |                                      |  |  |  |  |  |
| Appearance                         | No abnormal exterior appearance  | Microscope (×10)                     |  |  |  |  |  |
| Withstanding                       | No dielectric breakdown or   | 300% of the rated voltage            |  |  |  |  |  |
| Voltage                            | mechanical breakdown   |                                      |  |  |  |  |  |
| Temperature                        | COG  |                                      |  |  |  |  |  |
| Characterisitcs                    | (From -55 $^{\circ}\!$ |                                      |  |  |  |  |  |
| Adhesive Strength                  | No peeling shall be occur on the   | 500g·F, for 10±1 sec.                |  |  |  |  |  |
| of Termination                     | terminal electrode   |                                      |  |  |  |  |  |
| Bending Strength                   | Capacitance change :   | Bending to the limit (1mm)           |  |  |  |  |  |
|                                    | within ±5% or ±0.5pF whichever is larger   | with 1.0mm/sec.                      |  |  |  |  |  |
| Solderability                      | More than 75% of terminal surface  | SnAg3.0Cu0.5 solder                  |  |  |  |  |  |
|                                    | is to be soldered newly  | 245±5℃, 3±0.3sec.                    |  |  |  |  |  |
|                                    |  | (preheating : 80~120℃ for 10~30sec.) |  |  |  |  |  |
|                                    |  |                                      |  |  |  |  |  |
| Resistance to Capacitance change : |  | Solder pot : 270±5℃, 10±1sec.        |  |  |  |  |  |
| Soldering heat                     | within ±2.5% or ±0.25pF whichever is larger  |                                      |  |  |  |  |  |
|                                    | Tan δ, IR : initial spec.  |                                      |  |  |  |  |  |

|                  | Performance                                 | Test condition   |  |  |  |  |  |
|------------------|---|--|--|--|--|--|--|
| Vibration Test   | Capacitance change :                        | Amplitude: 1.5mm   |  |  |  |  |  |
|                  | within ±2.5% or ±0.25pF whichever is larger | From 10Hz to 55Hz (return : 1min.)   |  |  |  |  |  |
|                  | Tan δ, IR : initial spec.                   | 2hours × 3 direction (x, y, z)   |  |  |  |  |  |
| Moisture         | Capacitance change :                        | With rated voltage   |  |  |  |  |  |
| Resistance       | within ±7.5% or ±0.75pF whichever is larger | 40±2℃, 90~95%RH, 500+12/-0hrs  |  |  |  |  |  |
|                  | Q: 200 min                                  |  |  |  |  |  |  |
|                  | IR : 500Mohm or 25Mohm $\cdot \mu$ F        |  |  |  |  |  |  |
|                  | Whichever is Smaller                        |  |  |  |  |  |  |
| High Temperature | Capacitance change :                        | With 200% of the rated voltage   |  |  |  |  |  |
| Resistance       | within ±3% or ±0.3pF whichever is larger    | Max. operating temperature   |  |  |  |  |  |
|                  | Q: 350 min                                  | 1000+48/-0hrs  |  |  |  |  |  |
|                  | IR : 1000Mohm or 50Mohm $\cdot \mu$ F       |  |  |  |  |  |  |
|                  | Whichever is Smaller                        |  |  |  |  |  |  |
| Temperature      | Capacitance change :                        | 1 cycle condition  |  |  |  |  |  |
| Cycling          | within ±2.5% or ±0.25pF whichever is larger | Min. operating temperatur → 25 ℃   |  |  |  |  |  |
|                  | Tan δ, IR : initial spec.                   | $ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$ |  |  |  |  |  |
|                  |   |  |  |  |  |  |  |
|                  |   |  |  |  |  |  |  |
|                  |   | 5 cycle test   |  |  |  |  |  |

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.